

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1901	multilayer with wiring with copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:31
L2	793	multilayer with (wiring near4 copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:31
L3	127	multilayer with (wiring near4 copper) with resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:35
L4	0	multilayer with capacitor with (wiring near4 copper) with resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:35
L5	7	multilayer with capacitor with (wiring near4 copper)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:36
L6	0	(multilayer with (wiring near4 copper)) and capaciotr	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:47
L7	438	(multilayer with bump with ("IC" or chip or die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:48
L8	50	"361"/\$.ccls. and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/03 17:48